



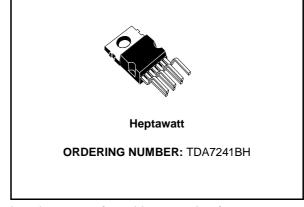
## 20W BRIDGE AMPLIFIER FOR CAR RADIO

- VERY LOW STAND-BY CURRENT
- GAIN = 32dB
- OUTPUT PROTECTED AGAINST SHORT CIRCUITS TO GROUND AND ACROSS LOAD
- COMPACT HEPTAWATT PACKAGE
- DUMP TRANSIENT
- THERMAL SHUTDOWN
- LOUDSPEAKER PROTECTION
- HIGH CURRENT CAPABILITY
- LOW DISTORTION / LOW NOISE

#### **DESCRIPTION**

The TDA7241B is a 20W bridge audio amplifier IC designed specially for car radio applications. Thanks to the low external part count and compact Heptawatt 7-pin power package the TDA7241B occupies little space on the printed circuit board.

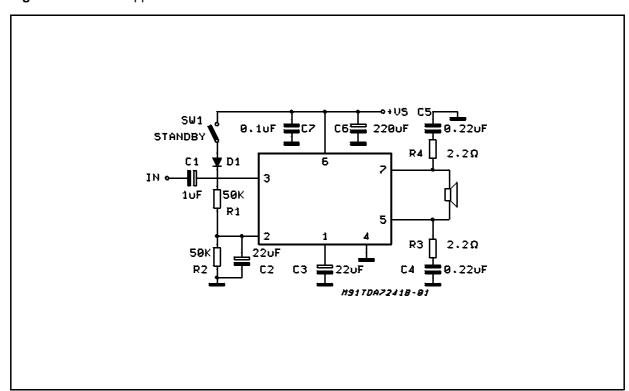
Reliable operation is guaranteed by a compre-



hensive array of on-chip protection features.

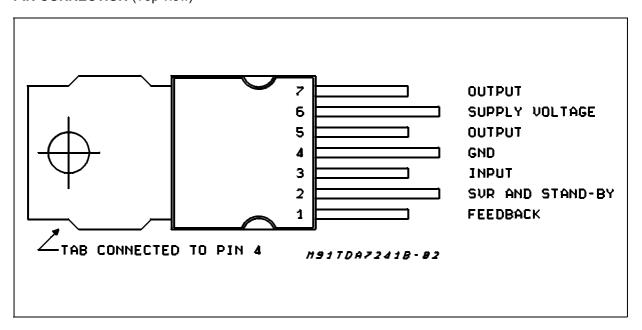
These include protection against AC and DC output short circuits (to ground and across the load), load dump transients, and junction overtemperature. Additionally, the TDA7241B protects the loudspeaker when one output is short-circuited to ground.

Figure 1: Test and Appliication Circuit



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## **PIN CONNECTION** (Top view)



## **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
Vs	Operating Supply Voltage	18	V
Vs	DC Supply Voltage	28	V
Vs	Peak Supply Voltage (t = 50ms)	40	V
lo	Peak Output Current (non repetitive t = 0.1ms)	4.5	Α
Io	Peak Output Current (repetitive f ≥ 10Hz)	3.5	Α
P <sub>tot</sub>	Power Dissipation at T <sub>case</sub> = 85°C	16	W
T <sub>stg</sub> , T <sub>j</sub>	Storage and Junction Temperature	-40 to 150	°C

#### **THERMAL DATA**

Ī	Symbol	Description			Unit
	R <sub>th j-case</sub>	Thermal Resistance Junction-case	Max	4	°C/W

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**ELECTRICAL CHARACTERISTICS** (Refer to the circuit of Fig. 1;  $V_S = 14.4V$ ;  $R_{th}$  (heatsink) =  $4^{\circ}C/W$ ,  $T_{amb} = 25^{\circ}C$ , unless otherwise specified

Symbol	Parameter Test Condition		Min.	Тур.	Max.	Unit
Vs	Supply Range				18	V
I <sub>d</sub>	Total Quiescent Current	Furrent $R_L = 4\Omega$			80	mA
Vos	Output Offset Voltage				100	mV
Po	Output Power	$ \begin{array}{c} R_L = 2\Omega \\ f = 1 \text{KHz}  d = 10\% \\ R_L = 4\Omega \\ R_L = 8\Omega \end{array} $	18	26 20 12		W
d	Distortion	$ \begin{array}{ccc} R_L = 4\Omega & f = 1 \text{KHz} \\ P_O = 50 \text{mW to } 12 \text{W} \end{array} $			0.5	%
		$R_L = 8\Omega$ $f = 1KHz$ $P_O = 50mW$ to $6W$		0.05		%
G <sub>V</sub>	Voltage Gain	f = 1KHz	31	32	33	dB
SVR	Supply Voltage Rejection	$f = 100Hz$ $R_g = 10K\Omega$	40	50		dB
En				2		μV
		B = 22Hz to 22KHz $R_S = 10K\Omega$		3	10	mV
η	Efficiency	$R_L = 4\Omega$ f = 1KHz $P_O = 20W$		65		%
I <sub>sb</sub>	Stand-by Current				100	μΑ
R <sub>i</sub>	Input Resistance	f = 1KHz	70			ΚΩ
Vi	Input Sensitivity	f = 1KHz $P_0 = 2W$ $R_L = 4\Omega$		70		mV
fL	Low Frequency Roll Off (-3dB)	$P_O = 15W$ $R_L = 4\Omega$		30		Hz
f <sub>H</sub>	High Frequency Roll Off (-3dB)	$PO = 15W$ $R_L = 4\Omega$	25			KHz
As	Stand-by Attenuation	V <sub>O</sub> = 2Vrms	70	90		dB
V <sub>TH</sub> (pin.2)	Stand-by Threshold				1	V
T <sub>sd</sub>	Thermal Shutdown Junction Temp.			150		°C

<sup>(\*)</sup> B = Curve (\*\*) B = 22Hz to 22KHz

Figure 2: P.C. Board and Component Layout of the Circuit of Fig. 1 (1:1 scale).

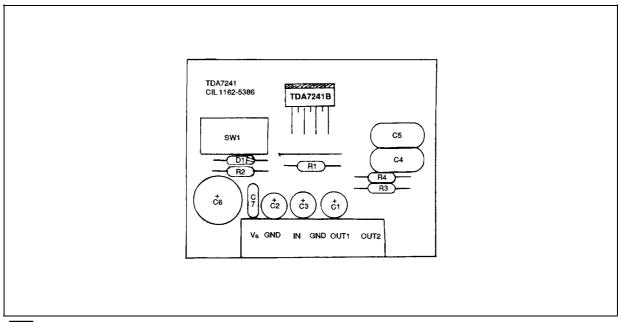


Figure 3: Output Power vs. Supply Voltage

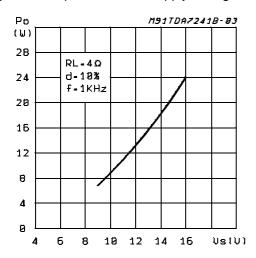


Figure 5: Distortion vs. Output Power

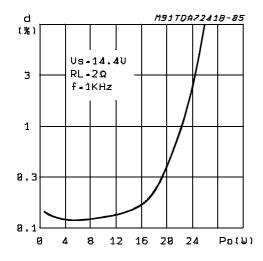


Figure 7: Distortion vs. Output Power

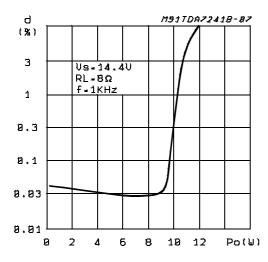


Figure 4: Output Power vs. Supply Voltage

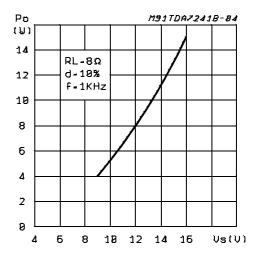


Figure 6: Distortion vs. Output Power

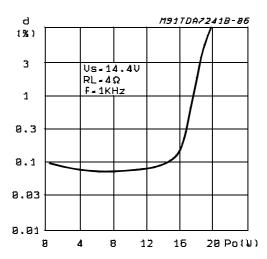
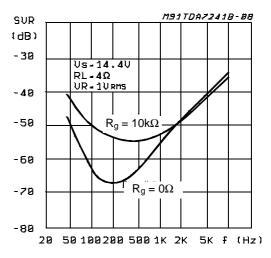
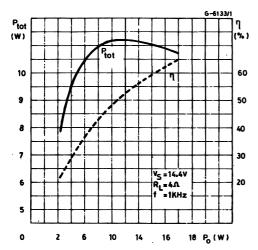


Figure 8: SVR vs. Frequency

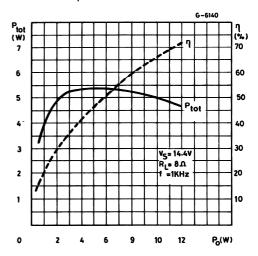


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**Figure 9:** Power Dissipation and Efficiency vs. Output Power

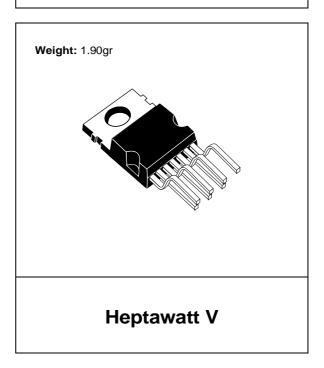


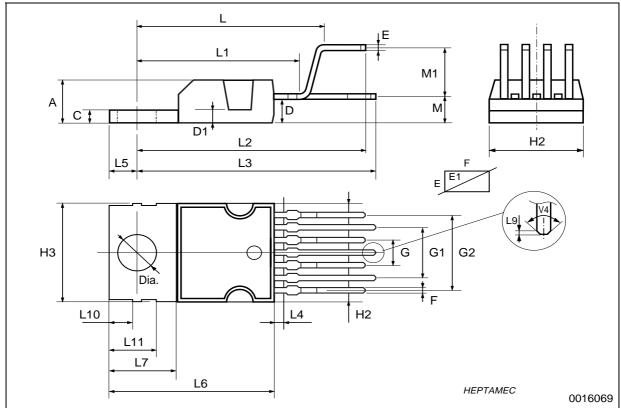
**Figure 10:** Power Dissipation and Efficiency vs. Output Power



DIM.	mm			inch			
DIN.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
Α			4.8			0.189	
С			1.37			0.054	
D	2.4		2.8	0.094		0.110	
D1	1.2		1.35	0.047		0.053	
Е	0.35		0.55	0.014		0.022	
E1	0.7		0.97	0.028		0.038	
F	0.6		0.8	0.024		0.031	
G	2.34	2.54	2.74	0.095	0.100	0.105	
G1	4.88	5.08	5.28	0.193	0.200	0.205	
G2	7.42	7.62	7.82	0.295	0.300	0.307	
H2			10.4			0.409	
H3	10.05		10.4	0.396		0.409	
L	16.7	16.9	17.1	0.657	0.668	0.673	
L1		14.92			0.587		
L2	21.24	21.54	21.84	0.386	0.848	0.860	
L3	22.27	22.52	22.77	0.877	0.891	0.896	
L4			1.29			0.051	
L5	2.6	2.8	3	0.102	0.110	0.118	
L6	15.1	15.5	15.8	0.594	0.610	0.622	
L7	6	6.35	6.6	0.236	0.250	0.260	
L9		0.2			0.008		
L10	2.1		2.7	0.082		0.106	
L11	4.3		4.8	0.169		0.190	
М	2.55	2.8	3.05	0.100	0.110	0.120	
M1	4.83	5.08	5.33	0.190	0.200	0.210	
V4	40 (typ.)						
Dia	3.65		3.85	0.144		0.152	

# OUTLINE AND MECHANICAL DATA





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